## **AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **LISTING OF CLAIMS:**

1. (Amended) A CVD apparatus comprising:

a vacuum vessel separated into two chambers;

the first one of the two chambers containing a radio-frequency electrode;

the second one of the two chamber containing a substrate support mechanism for mounting a substrate;

wherein said vacuum vessel is separated by an electrically conductive partitioning section, said partitioning section comprising:

a plurality of through-holes to allow communication between the first chamber and the second chamber;

an interior space for receiving a reactive gas, the interior space separated from the first chamber and communicating with the second chamber through a plurality of diffusion holes; and

a heater for heating the electrically conductive partition partitioning section.

2. (Original) The apparatus of claim 1, further comprising:

an electrically conductive spiral shield; and

wherein the partitioning section is mounted to the vacuum vessel by means of a mounting screw such that electrical contact between the partitioning section and the vacuum vessel is achieved through said spiral shield.

- 3. (Original) A CVD apparatus comprising:
- a vacuum vessel separated into two chambers;

at least one radio-frequency electrode contained in a first one of said two chambers;

a substrate support mechanism contained in the second one of said two chambers;

an electrically conductive partition section;

an electrically conductive spiral shield; and

wherein said vacuum vessel is separated into two chambers by said electrically conductive partition section which is mounted to said vacuum vessel by means of a mounting screw such that electrical contact between the partitioning section and the vacuum vessel is achieved through said spiral shield.

- 4. (New) The apparatus of claim 1, wherein the heater is adapted to heat the partitioning section to at least 100°C.
- 5. (New) The apparatus of claim 1, wherein the heater is adapted to heat the partitioning section to at least 200°C.
- 6. (New) The apparatus of claim 1, wherein the heater is adapted to heat the partitioning section to a temperature at which the adsorption of fluorine onto an inner circumferential face of the through-holes and a surface of the partitioning section is suppressed.